NGTB30N65IHL2WG

IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. The IGBT is well suited for half bridge resonant applications. Incorporated into the device is a soft and fast co−packaged free wheeling diode with a low forward voltage.

Features

- Extremely Efficient Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Losses in IH Cooker Application
- T_{Jmax} = 175°C
- Soft, Fast Free Wheeling Diode
- This is a Pb−Free Device

Typical Applications

- Inductive Heating
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector−emitter voltage	V_{CES}	650	V
Collector current @ T_C = 25°C @ T_C = 100°C	I_C	 60 30	A
Pulsed collector current, T_{pulse} limited by T_{Jmax}	I_{CM}	120	A
Diode forward current @ T_C = 25°C @ T_C = 100°C	I_F	 60 30	A
Diode pulsed current, T_{pulse} limited by T_{Jmax}	I_{FM}	120	A
Gate−emitter voltage	V_{GE}	±20	V
Power Dissipation @ T_C = 25°C @ T_C = 100°C	P_D	 300 150	W
Operating junction temperature range	T_J	−55 to +175	°C
Storage temperature range	T_{stg}	−55 to +175	°C
Lead temperature for soldering, 1/8” from case for 5 seconds	T_{SLD}	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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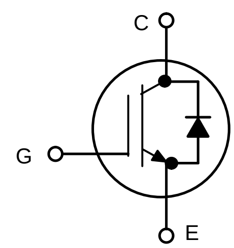
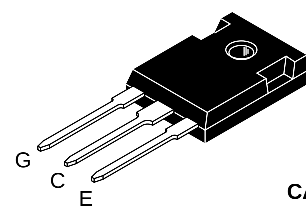
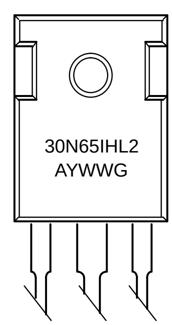
30 A, 650 V
V_{CEsat} = 1.6 V
E_{off} = 0.2 mJ





TO−247
CASE 340AL

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
G = Pb−Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB30N65IHL2WG	TO−247 (Pb−Free)	30 Units / Rail

June, 2014 − Rev. 0
Publication Order Number:
NGTB30N65IHL2W/D

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction−to−case, for IGBT	$R_{\theta JC}$	0.50	°C/W
Thermal resistance junction−to−case, for Diode	$R_{\theta JC}$	1.46	°C/W
Thermal resistance junction−to−ambient	$R_{\theta JA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
STATIC CHARACTERISTIC						
Collector−emitter breakdown voltage, gate−emitter short−circuited	V_{GE} = 0 V, I_C = 500 μA	$V_{(BR)CES}$	650	−	−	V
Collector−emitter saturation voltage	V_{GE} = 15 V, I_C = 30 A V_{GE} = 15 V, I_C = 30 A, T_J = 175°C	V_{CEsat}	− −	1.6 2.0	2.2 −	V
Gate−emitter threshold voltage	V_{GE} = V_{CE}, I_C = 150 μA	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector−emitter cut−off current, gate−emitter short−circuited	V_{GE} = 0 V, V_{CE} = 650 V V_{GE} = 0 V, V_{CE} = 650 V, T_J = 175°C	I_{CES}	− −	− −	0.2 2	mA
Gate leakage current, collector−emitter short−circuited	V_{GE} = 20 V , V_{CE} = 0 V	I_{GES}	−	−	100	nA
DYNAMIC CHARACTERISTIC						
Input capacitance	V_{CE} = 20 V, V_{GE} = 0 V, f = 1 MHz	C_{ies}	−	3200	−	pF
Output capacitance		C_{oes}	−	130	−	
Reverse transfer capacitance		C_{res}	−	85	−	
Gate charge total	V_{CE} = 480 V, I_C = 30 A, V_{GE} = 15 V	Q_g		135		nC
Gate to emitter charge		Q_{ge}		26		
Gate to collector charge		Q_{gc}		66		
SWITCHING CHARACTERISTIC, INDUCTIVE LOAD						
Turn−off delay time	T_J = 25°C V_{CC} = 400 V, I_C = 30 A R_g = 10 Ω V_{GE} = 0 V/ 15V	$t_{d(off)}$		145		ns
Fall time		t_f		71		
Turn−off switching loss		E_{off}		0.2		mJ
Turn−off delay time	T_J = 150°C V_{CC} = 400 V, I_C = 30 A R_g = 10 Ω V_{GE} = 0 V/ 15V	$t_{d(off)}$		151		ns
Fall time		t_f		94		
Turn−off switching loss		E_{off}		0.41		mJ
DIODE CHARACTERISTIC						
Forward voltage	V_{GE} = 0 V, I_F = 30 A V_{GE} = 0 V, I_F = 30 A, T_J = 175°C	V_F		1.1 1.0	1.3	V
Reverse recovery time	T_J = 25°C I_F = 30 A, V_R = 200 V di_F/dt = 200 A/μs	t_{rr}		430		ns
Reverse recovery charge		Q_{rr}		7700		nc
Reverse recovery current		I_{rrm}		35		A

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

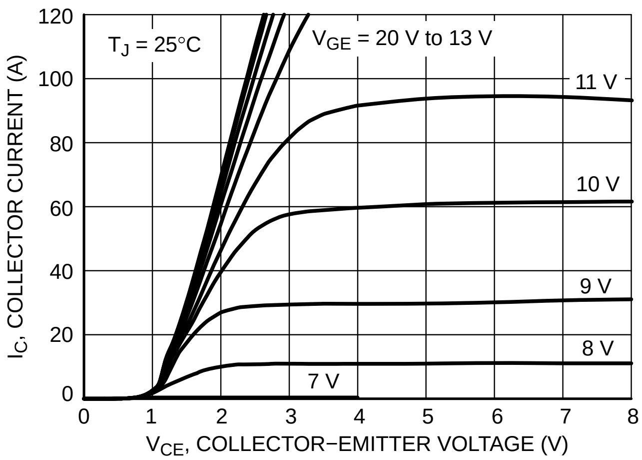


Figure 1. Output Characteristics

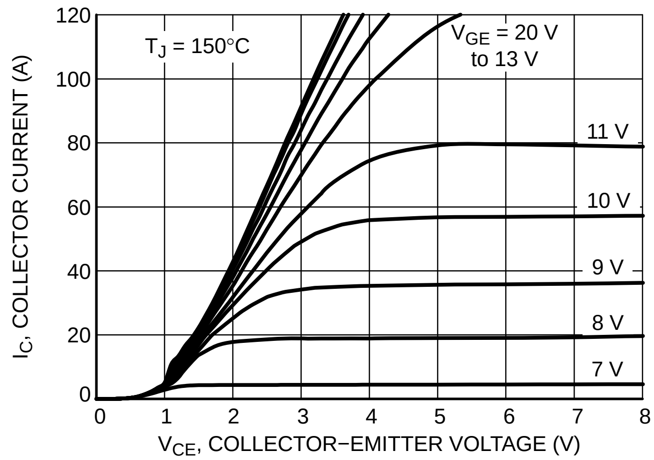


Figure 2. Output Characteristics

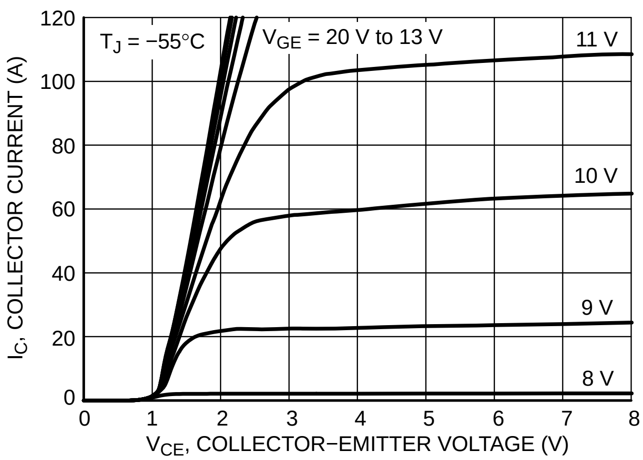


Figure 3. Output Characteristics

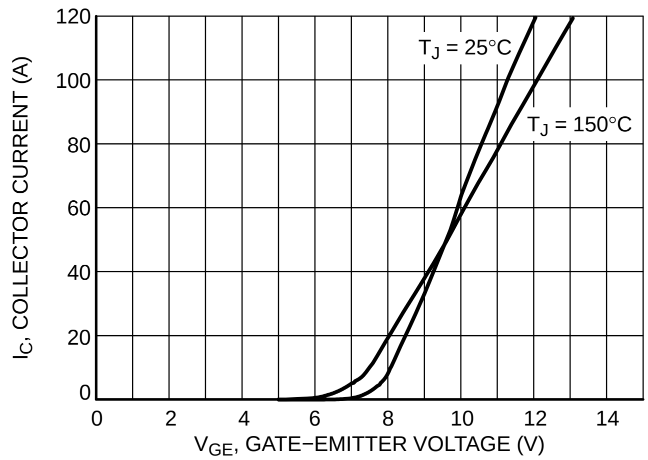


Figure 4. Typical Transfer Characteristics

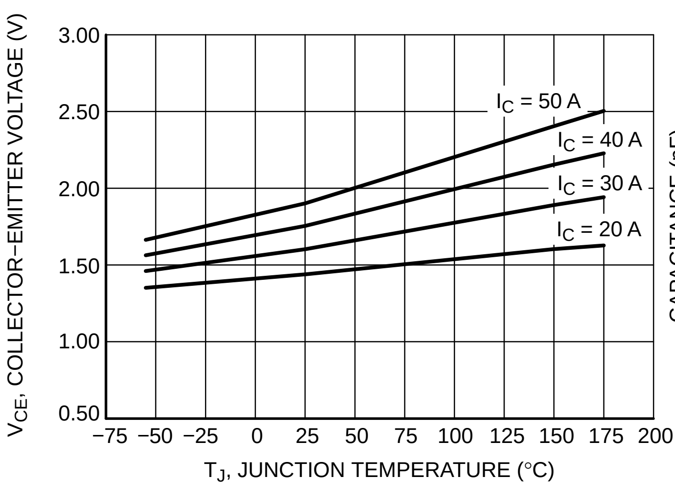


Figure 5. $V_{CE(sat)}$ vs. T_J

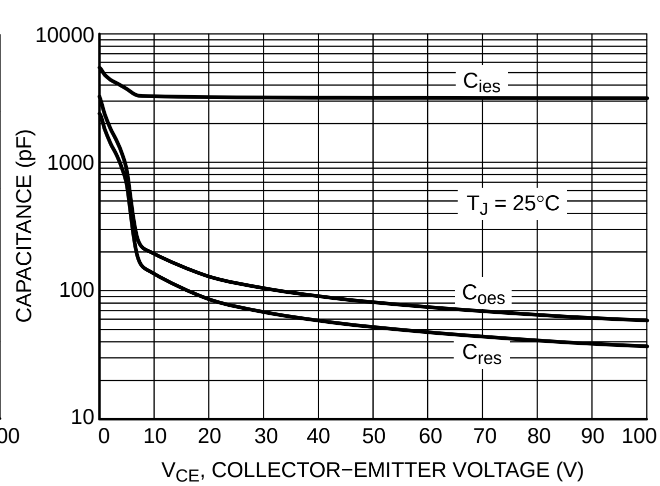


Figure 6. Typical Capacitance

TYPICAL CHARACTERISTICS

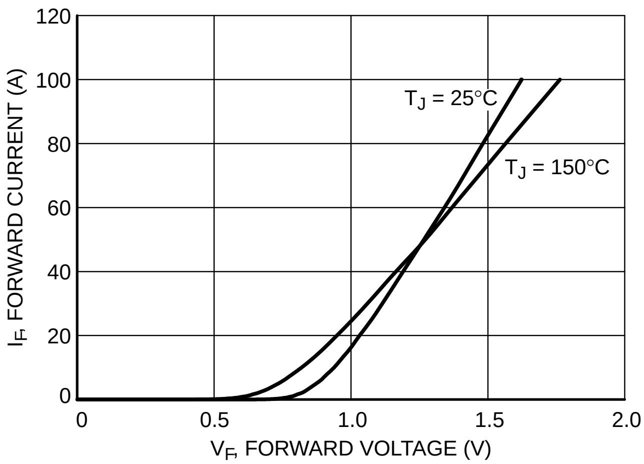


Figure 7. Diode Forward Characteristics

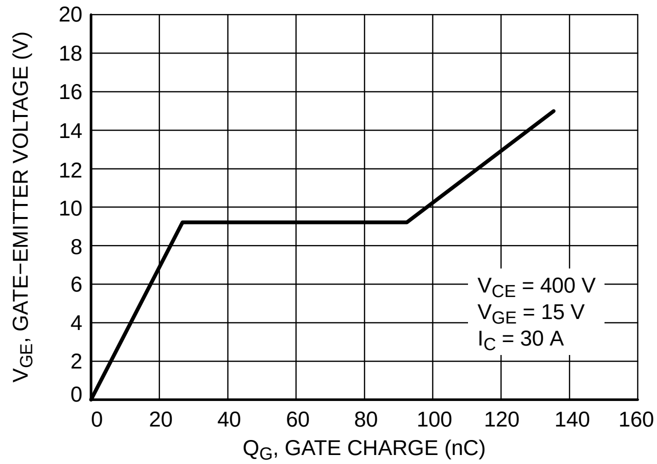


Figure 8. Typical Gate Charge

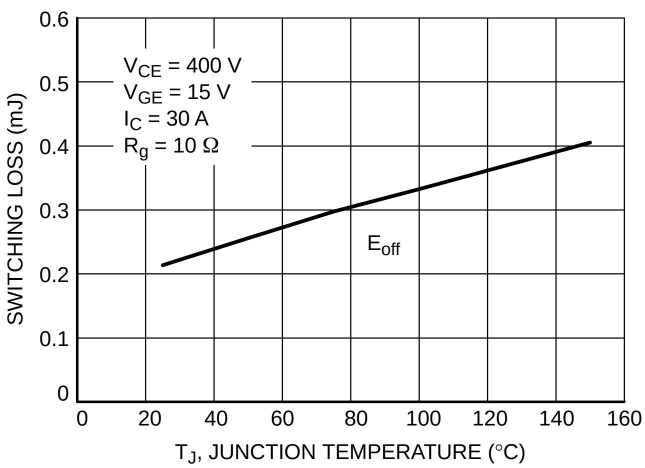


Figure 9. Switching Loss vs. Temperature

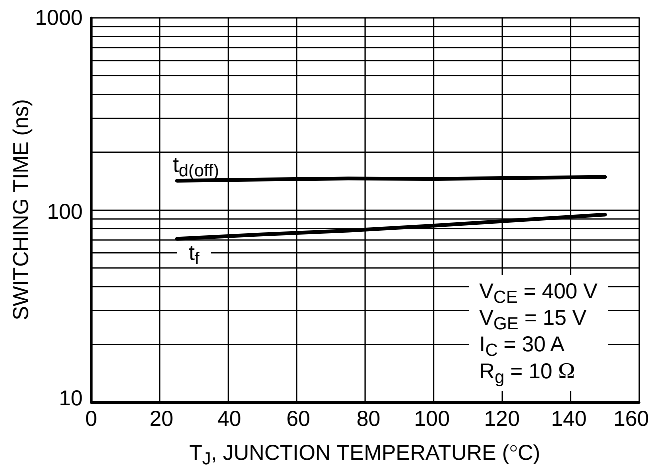


Figure 10. Switching Time vs. Temperature

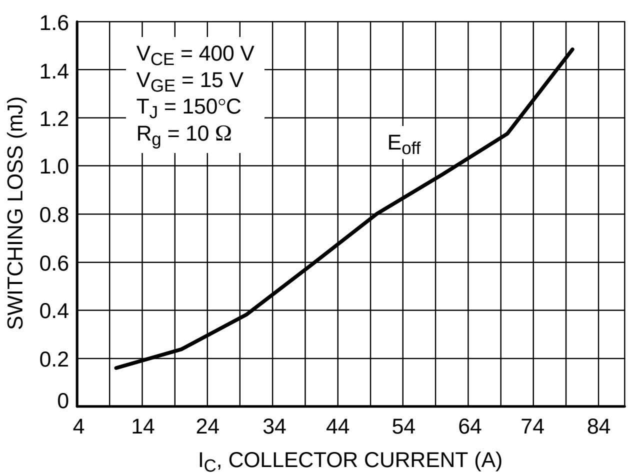


Figure 11. Switching Loss vs. I_C

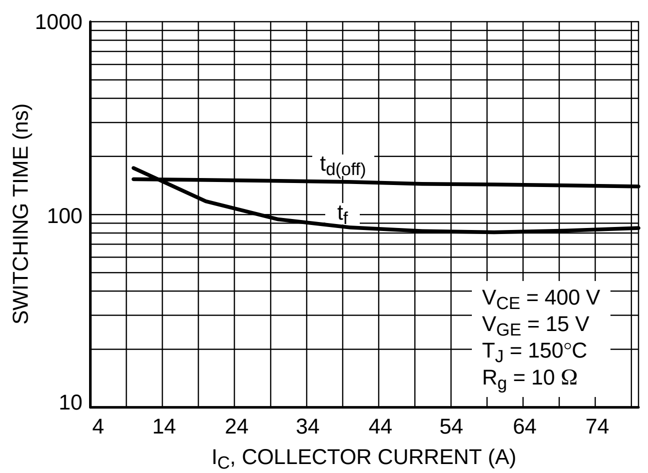


Figure 12. Switching Time vs. I_C

TYPICAL CHARACTERISTICS

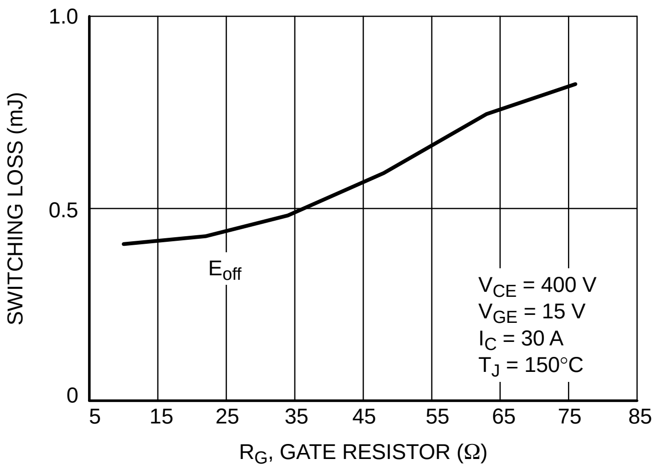


Figure 13. Switching Loss vs. R_G

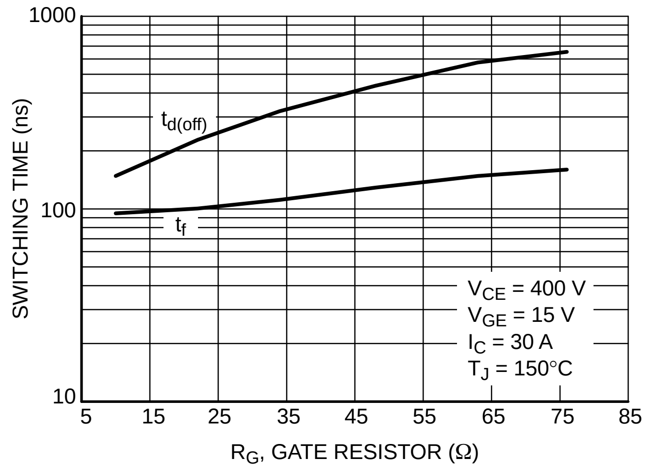


Figure 14. Switching Time vs. R_G

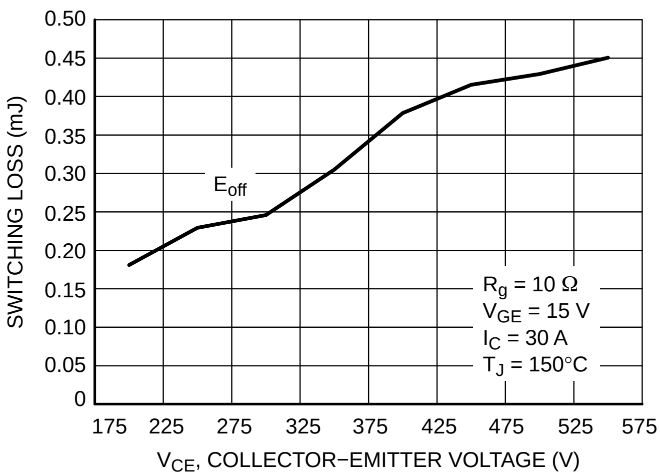


Figure 15. Switching Loss vs. V_{CE}

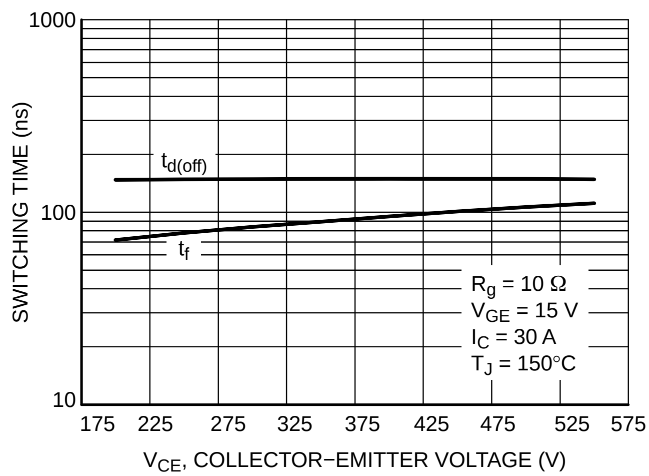


Figure 16. Switching Time vs. V_{CE}

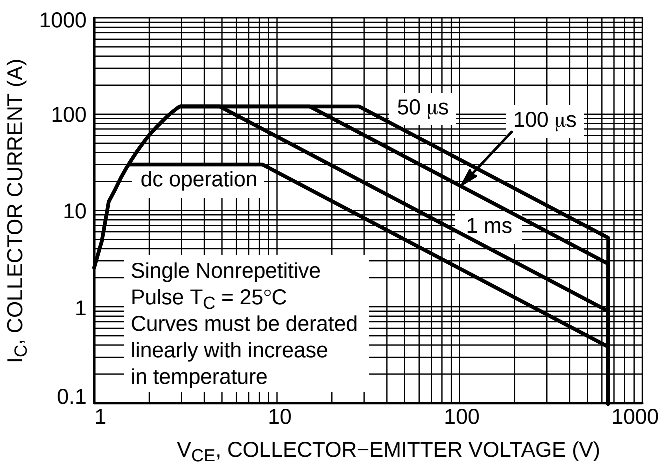


Figure 17. Safe Operating Area

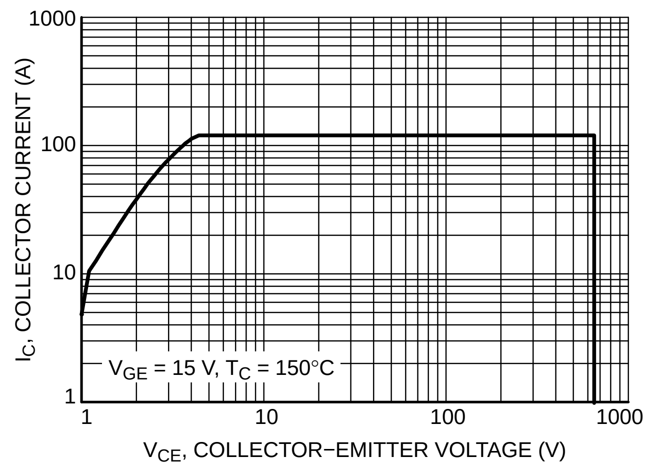
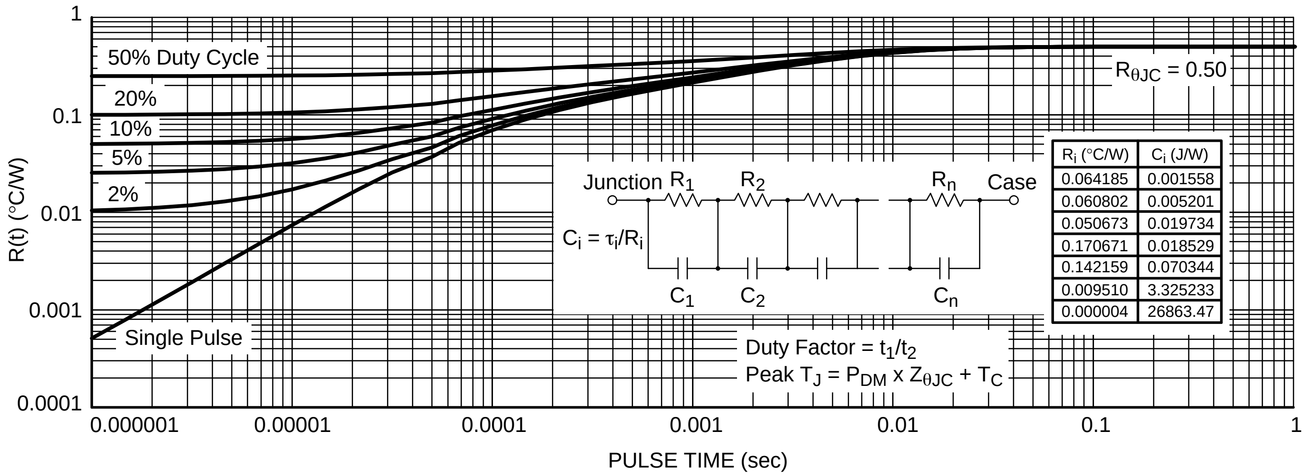


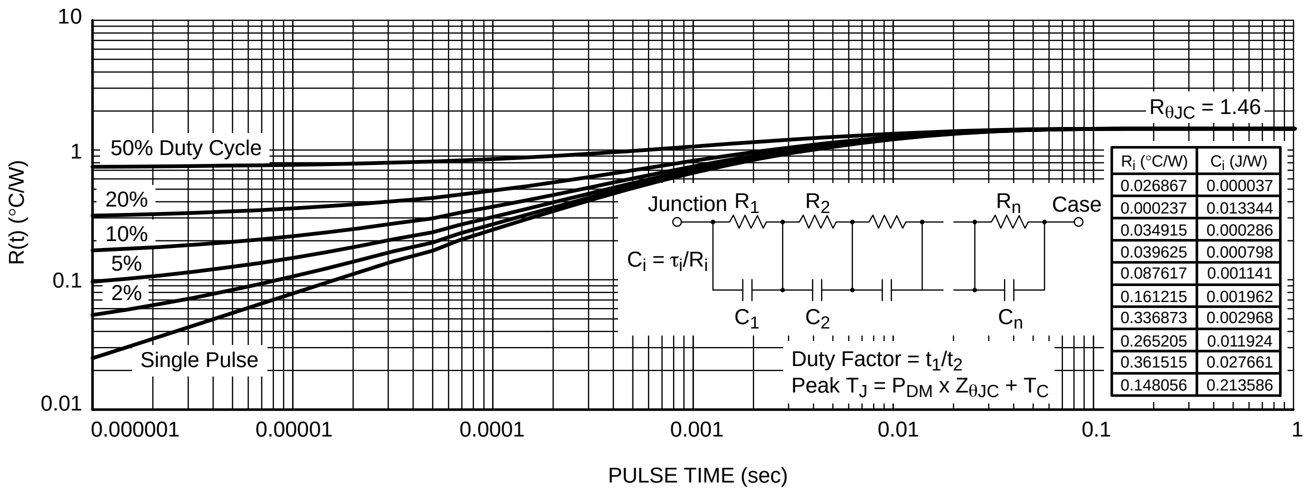
Figure 18. Reverse Bias Safe Operating Area

TYPICAL CHARACTERISTICS



R_i (°C/W)	C_i (J/W)
0.064185	0.001558
0.060802	0.005201
0.050673	0.019734
0.170671	0.018529
0.142159	0.070344
0.009510	3.325233
0.000004	26863.47

Figure 19. IGBT Transient Thermal Impedance



R_i (°C/W)	C_i (J/W)
0.026867	0.000037
0.000237	0.013344
0.034915	0.000286
0.039625	0.000798
0.087617	0.001141
0.161215	0.001962
0.336873	0.002968
0.265205	0.011924
0.361515	0.027661
0.148056	0.213586

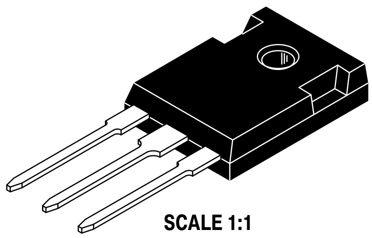
Figure 20. Diode Transient Thermal Impedance

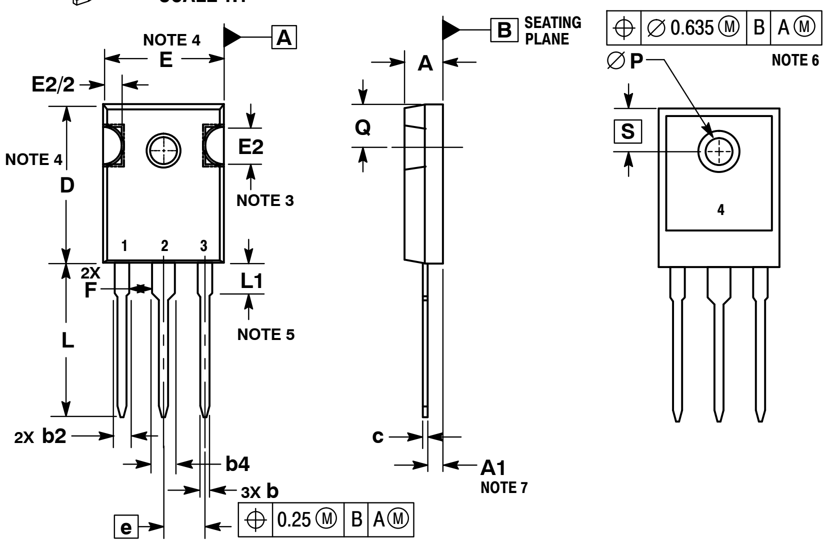
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

TO−247
CASE 340AL
ISSUE D

DATE 17 MAR 2017

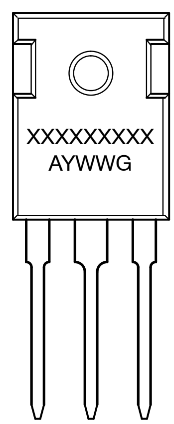




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. SLOT REQUIRED, NOTCH MAY BE ROUNDED.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
5. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.
6. ∅P SHALL HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91.
7. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.

	MILLIMETERS	
DIM	MIN	MAX
A	4.70	5.30
A1	2.20	2.60
b	1.07	1.33
b2	1.65	2.35
b4	2.60	3.40
c	0.45	0.68
D	20.80	21.34
E	15.50	16.25
E2	4.32	5.49
e	5.45 BSC	
F	2.655	---
L	19.80	20.80
L1	3.81	4.32
P	3.55	3.65
Q	5.40	6.20
S	6.15 BSC	

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking.
Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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DESCRIPTION:	**TO−247**	**PAGE 1 OF 1**

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